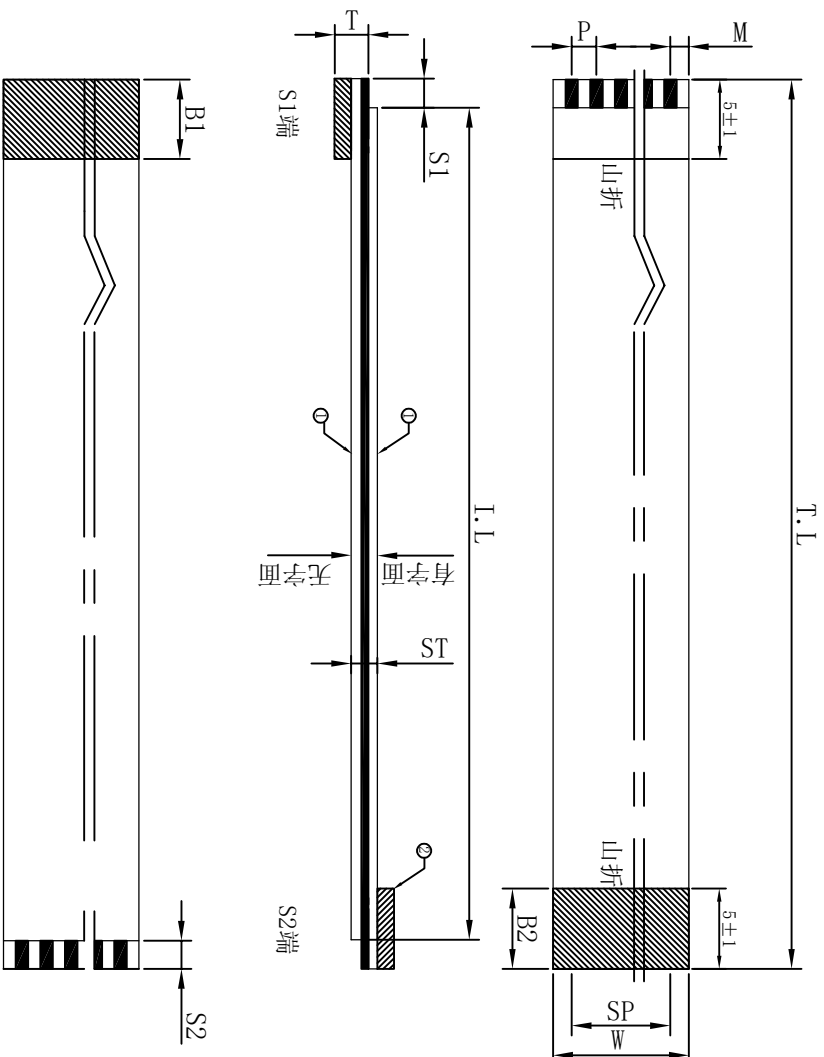




		8	9	0	
	STRUCTURE				
NO	ITEM NAME	SPECIFICATION	REMARK		
1	INSULATION (绝缘层)	印字UL20624 43um印字膜	80°C,60V		
		空白43um			
印字					
2	P /TAPE (补强板)	225um	深藍		
3	CONDUCTOR (鍍錫线)	THICKNESS	0.05	±0.005	
		WIDTH	0.8	±0.02	
	CONDUCTOR (导体镀层)	PLATED	SN(40u")	MIN	
		PLATED			

DIMENSION				
PITCH (间距)	P	2.54	±0.1	
SPAN(全间距)	SP	38.10	±0.15	
WIDTH(总宽度)	W	43.18	±0.15	
MARGIN(边距)	M	2.54	±0.15	
INSERT THICKNESS (插入厚度)	T	0.32	±0.05	
SURFACE THICKNESS (线身厚度)	ST	0.14	±0.03	
PROTECTOR LENGTH (补强板长度)	B1	10.0	±2.0	
	B2	10.0	±2.0	
STRIP LENGTH (金手指长度)	S1	5.0	±1.0	
	S2	5.0	±1.0	
INSULATION LENGTH (绝缘层长度)	I.L	143	±2.0	
TOTAL LENGTH (产品总长度)	T.L	153	±2.0	
NO. of PIN(导体数量)	16P			

NOTES:

1. 成品之两端内外CB为0--0.5mm
- 2.

HECON		P/N		东莞市禾康电子有限公司 DONGGUAN HECON ELECTRONICS CO., LTD	
HC-FTC-254-16-XXX-B-0X					
		TITLE		2. 54*16P*1.53-5/5/10/10 B	
		APPROVED			
		CHECKED			
		DRAWN			
		Bo Feng			
SER	DESCRIPTION	CHK	DATE	UNIT mm	SIZE XX
					SHEET
					1/1